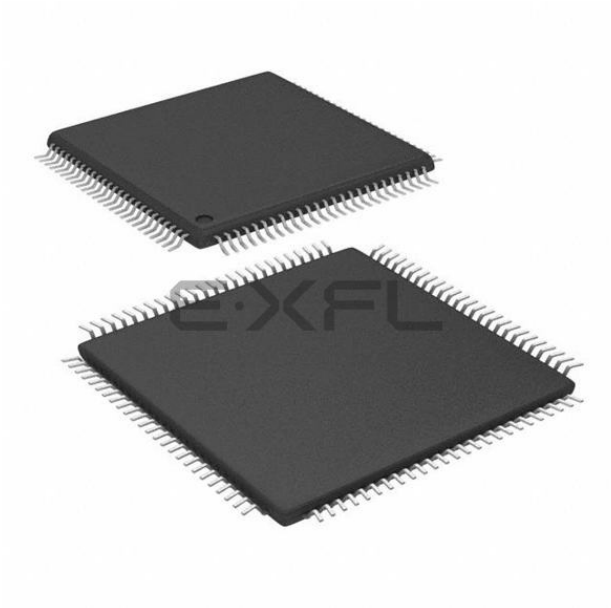

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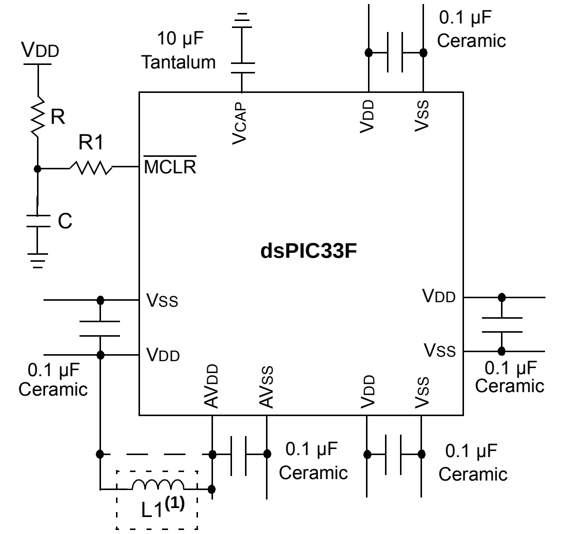
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	85
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64mc710at-i-pt

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2} \quad \text{(i.e., ADC conversion rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 26.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 23.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides for two specific device functions:

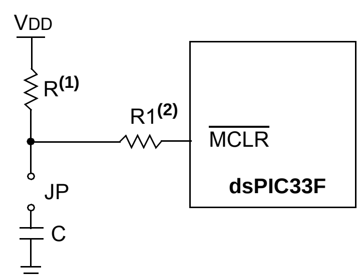
- Device Reset
- Device Programming and Debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{\text{MCLR}}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

TABLE 4-25: ECAN2 REGISTER MAP WHEN WIN (C1CTRL<0>) = 1 FOR dsPIC33FJXXXMC708A/710A DEVICES (CONTINUED)

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C2RXF11SID	056C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF11EID	056E	EID<15:8>								EID<7:0>								xxxx
C2RXF12SID	0570	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF12EID	0572	EID<15:8>								EID<7:0>								xxxx
C2RXF13SID	0574	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF13EID	0576	EID<15:8>								EID<7:0>								xxxx
C2RXF14SID	0578	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF14EID	057A	EID<15:8>								EID<7:0>								xxxx
C2RXF15SID	057C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF15EID	057E	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-26: PORTA REGISTER MAP[1]

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	TRISA15	TRISA14	—	—	—	TRISA10	TRISA9	—	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	C6FF
PORTA	02C2	RA15	RA14	—	—	—	RA10	RA9	—	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	02C4	LATA15	LATA14	—	—	—	LATA10	LATA9	—	LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA[2]	06C0	ODCA15	ODCA14	—	—	—	—	—	—	—	—	ODCA5	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal for high pin count devices.

Note 1: The actual set of I/O port pins varies from one device to another. Please refer to the corresponding pinout diagrams.

TABLE 4-27: PORTB REGISTER MAP[1]

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C6	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	02C8	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	02CA	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal for high pin count devices.

Note 1: The actual set of I/O port pins varies from one device to another. Please refer to the corresponding pinout diagrams.

4.4.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. It is important to realize that the address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes may, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset (e.g., [W7+W2]) is used, Modulo Address correction is performed but the contents of the register remain unchanged.

4.5 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which may be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order; thus, the only operand requiring reversal is the modifier.

4.5.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled when the following conditions exist:

1. The BWM bits (W register selection) in the MODCON register are any value other than 15 (the stack cannot be accessed using Bit-Reversed Addressing).
2. The BREN bit is set in the XBREV register.
3. The addressing mode used is Register Indirect with Pre-Increment or Post-Increment.

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last 'N' bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Address modifier, or 'pivot point,' which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note:	All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is only executed for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It will not function for any other addressing mode or for byte-sized data; normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	Modulo Addressing and Bit-Reversed Addressing should not be enabled together. In the event that the user attempts to do so, Bit-Reversed Addressing will assume priority for the X WAGU, and X WAGU Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN bit (XBREV<15>), then a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

EXAMPLE 5-2: LOADING THE WRITE BUFFERS

```
; Set up NVMCON for row programming operations
       MOV     #0x4001, W0                      ;
       MOV     W0, NVMCON                       ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0                      ;
       MOV     W0, TBLPAG                       ; Initialize PM Page Boundary SFR
       MOV     #0x6000, W0                      ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2                  ;
       MOV     #HIGH_BYTE_0, W3                 ;
       TBLWTL  W2, [W0]                         ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                       ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2                  ;
       MOV     #HIGH_BYTE_1, W3                 ;
       TBLWTL  W2, [W0]                         ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                       ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2                  ;
       MOV     #HIGH_BYTE_2, W3                 ;
       TBLWTL  W2, [W0]                         ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                       ; Write PM high byte into program latch
       •
       •
       •
; 63rd_program_word
       MOV     #LOW_WORD_31, W2                 ;
       MOV     #HIGH_BYTE_31, W3                ;
       TBLWTL  W2, [W0]                         ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                       ; Write PM high byte into program latch
```

EXAMPLE 5-3: INITIATING A PROGRAMMING SEQUENCE

```
       DISI    #5                       ; Block all interrupts with priority <7
                                        ; for next 5 instructions
       MOV     #0x55, W0
       MOV     W0, NVMKEY               ; Write the 55 key
       MOV     #0xAA, W1                ;
       MOV     W1, NVMKEY               ; Write the AA key
       BSET    NVMCON, #WR              ; Start the erase sequence
       NOP                              ; Insert two NOPs after the
       NOP                              ; erase command is asserted
```

TABLE 7-1: INTERRUPT VECTORS

Vector Number	Interrupt Request (IRQ) Number	IVT Address	AIVT Address	Interrupt Source
8	0	0x000014	0x000114	INT0 – External Interrupt 0
9	1	0x000016	0x000116	IC1 – Input Capture 1
10	2	0x000018	0x000118	OC1 – Output Compare 1
11	3	0x00001A	0x00011A	T1 – Timer1
12	4	0x00001C	0x00011C	DMA0 – DMA Channel 0
13	5	0x00001E	0x00011E	IC2 – Input Capture 2
14	6	0x000020	0x000120	OC2 – Output Compare 2
15	7	0x000022	0x000122	T2 – Timer2
16	8	0x000024	0x000124	T3 – Timer3
17	9	0x000026	0x000126	SPI1E – SPI1 Error
18	10	0x000028	0x000128	SPI1 – SPI1 Transfer Done
19	11	0x00002A	0x00012A	U1RX – UART1 Receiver
20	12	0x00002C	0x00012C	U1TX – UART1 Transmitter
21	13	0x00002E	0x00012E	ADC1 – ADC 1
22	14	0x000030	0x000130	DMA1 – DMA Channel 1
23	15	0x000032	0x000132	Reserved
24	16	0x000034	0x000134	SI2C1 – I2C1 Slave Events
25	17	0x000036	0x000136	MI2C1 – I2C1 Master Events
26	18	0x000038	0x000138	Reserved
27	19	0x00003A	0x00013A	Change Notification Interrupt
28	20	0x00003C	0x00013C	INT1 – External Interrupt 1
29	21	0x00003E	0x00013E	ADC2 – ADC 2
30	22	0x000040	0x000140	IC7 – Input Capture 7
31	23	0x000042	0x000142	IC8 – Input Capture 8
32	24	0x000044	0x000144	DMA2 – DMA Channel 2
33	25	0x000046	0x000146	OC3 – Output Compare 3
34	26	0x000048	0x000148	OC4 – Output Compare 4
35	27	0x00004A	0x00014A	T4 – Timer4
36	28	0x00004C	0x00014C	T5 – Timer5
37	29	0x00004E	0x00014E	INT2 – External Interrupt 2
38	30	0x000050	0x000150	U2RX – UART2 Receiver
39	31	0x000052	0x000152	U2TX – UART2 Transmitter
40	32	0x000054	0x000154	SPI2E – SPI2 Error
41	33	0x000056	0x000156	SPI1 – SPI1 Transfer Done
42	34	0x000058	0x000158	C1RX – ECAN1 Receive Data Ready
43	35	0x00005A	0x00015A	C1 – ECAN1 Event
44	36	0x00005C	0x00015C	DMA3 – DMA Channel 3
45	37	0x00005E	0x00015E	IC3 – Input Capture 3
46	38	0x000060	0x000160	IC4 – Input Capture 4
47	39	0x000062	0x000162	IC5 – Input Capture 5
48	40	0x000064	0x000164	IC6 – Input Capture 6
49	41	0x000066	0x000166	OC5 – Output Compare 5
50	42	0x000068	0x000168	OC6 – Output Compare 6
51	43	0x00006A	0x00016A	OC7 – Output Compare 7
52	44	0x00006C	0x00016C	OC8 – Output Compare 8
53	45	0x00006E	0x00016E	Reserved

REGISTER 7-7: IFS2: INTERRUPT FLAG STATUS REGISTER 2

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T6IF	DMA4IF	—	OC8IF	OC7IF	OC6IF	OC5IF	IC6IF
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC5IF	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF	SPI2IF	SPI2EIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **T6IF:** Timer6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 14 **DMA4IF:** DMA Channel 4 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 13 **Unimplemented:** Read as ‘0’

bit 12 **OC8IF:** Output Compare Channel 8 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **OC7IF:** Output Compare Channel 7 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10 **OC6IF:** Output Compare Channel 6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 9 **OC5IF:** Output Compare Channel 5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 8 **IC6IF:** Input Capture Channel 6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7 **IC5IF:** Input Capture Channel 5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **IC4IF:** Input Capture Channel 4 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **IC3IF:** Input Capture Channel 3 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **DMA3IF:** DMA Channel 3 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **C1IF:** ECAN1 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

10.0 POWER-SAVING FEATURES

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJXXXMCX06A/X08A/X10A devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. dsPIC33FJXXXMCX06A/X08A/X10A devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

dsPIC33FJXXXMCX06A/X08A/X10A devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

dsPIC33FJXXXMCX06A/X08A/X10A devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the `PWRSAV` instruction is shown in Example 10-1.

> **Note:** `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode has the following features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items such as the input change notification on the I/O ports and peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation is disabled in Sleep mode.

The device will wake-up from Sleep mode on any of the following events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV  #IDLE_MODE     ; Put the device into IDLE mode
```


10.2.2 IDLE MODE

Idle mode has the following features:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device will wake from Idle mode on any of the following events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the `PWRSAV` instruction or the first instruction in the ISR.

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a `PWRSAV` instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

10.3 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

It is also possible to use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is now placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable registers (PMD) provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled via the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers will have no effect and read values will be invalid.

A peripheral module is only enabled if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

Note:	If a PMD bit is set, the corresponding module is disabled after a delay of 1 instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of 1 instruction cycle (assuming the module control registers are already configured to enable module operation).

REGISTER 16-4: PxSECMP: PWMx SPECIAL EVENT COMPARE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTDIR[1]	SEVTCMP<14:8>[2]						
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<7:0>[2]							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **SEVTDIR:** Special Event Trigger Time Base Direction bit[1]
`1` = A Special Event Trigger will occur when the PWM time base is counting downwards
`0` = A Special Event Trigger will occur when the PWM time base is counting upwards

bit 14-0 **SEVTCMP<14:0>:** Special Event Compare Value bits[2]

Note 1: SEVTDIR is compared with PTDIR (PTMR<15>) to generate the Special Event Trigger.
2: SEVTCMP<14:0> is compared with PTMR<14:0> to generate the Special Event Trigger.

REGISTER 18-3: SPIxCON2: SPIx CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
FRMEN	SPIFSD	FRMPOL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	FRMDLY	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FRMEN:** Framed SPIx Support bit
1 = Framed SPIx support enabled ($\overline{\text{SSx}}$ pin used as frame Sync pulse input/output)
0 = Framed SPIx support disabled

bit 14 **SPIFSD:** Frame Sync Pulse Direction Control bit
1 = Frame Sync pulse input (slave)
0 = Frame Sync pulse output (master)

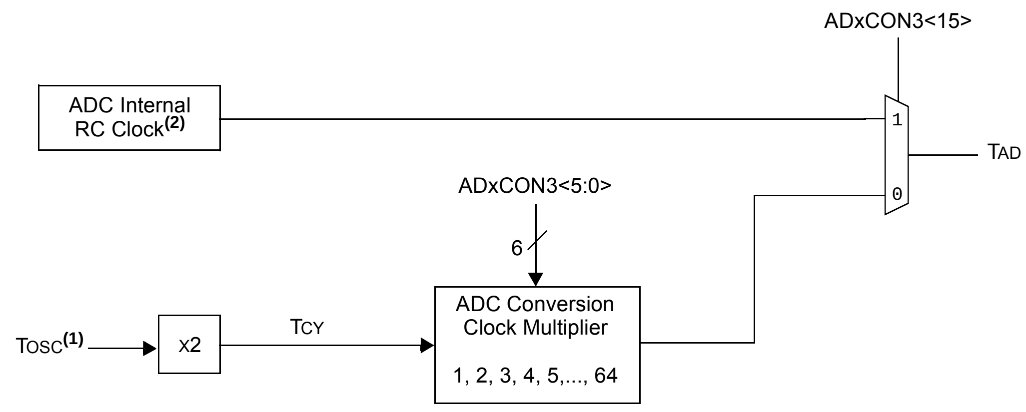
bit 13 **FRMPOL:** Frame Sync Pulse Polarity bit
1 = Frame Sync pulse is active-high
0 = Frame Sync pulse is active-low

bit 12-2 **Unimplemented:** Read as ‘0’

bit 1 **FRMDLY:** Frame Sync Pulse Edge Select bit
1 = Frame Sync pulse coincides with first bit clock
0 = Frame Sync pulse precedes first bit clock

bit 0 **Unimplemented:** This bit must not be set to ‘1’ by the user application.

FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: Refer to Figure 9-2 for the derivation of FOSC when the PLL is enabled. If the PLL is not used, FOSC is equal to the clock source frequency, TOSC = 1/FOSC.

2: See the ADC electrical specifications for the exact RC clock value.

TABLE 23-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Register	RTSP Effect	Description
BWRP	FBS	Immediate	Boot Segment Program Flash Write Protection bit 1 = Boot segment may be written 0 = Boot segment is write-protected
BSS<2:0>	FBS	Immediate	Boot Segment Program Flash Code Protection Size bits x11 = No boot program Flash segment Boot space is 1K IW less VS: 110 = Standard security; boot program Flash segment starts at end of VS, ends at 0007FEh 010 = High security; boot program Flash segment starts at end of VS, ends at 0007FEh Boot space is 4K IW less VS: 101 = Standard security; boot program Flash segment starts at end of VS, ends at 001FFEh 001 = High security; boot program Flash segment starts at end of VS, ends at 001FFEh Boot space is 8K IW less VS: 100 = Standard security; boot program Flash segment starts at end of VS, ends at 003FFEh 000 = High security; boot program Flash segment starts at end of VS, ends at 003FFEh
RBS<1:0>	FBS	Immediate	Boot Segment RAM Code Protection bits 11 = No boot RAM defined 10 = Boot RAM is 128 bytes 01 = Boot RAM is 256 bytes 00 = Boot RAM is 1024 bytes
SWRP	FSS	Immediate	Secure Segment Program Flash Write Protection bit 1 = Secure segment may be written 0 = Secure segment is write-protected

TABLE 23-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Register	RTSP Effect	Description
SSS<2:0>	FSS	Immediate	Secure Segment Program Flash Code Protection Size bits **(FOR 128K and 256K DEVICES)** X11 = No secure program Flash segment Secure space is 8K IW less BS: 110 = Standard security; secure program Flash segment starts at end of BS, ends at 0x003FFE 010 = High security; secure program Flash segment starts at end of BS, ends at 0x003FFE Secure space is 16K IW less BS: 101 = Standard security; secure program Flash segment starts at end of BS, ends at 0x007FFE 001 = High security; secure program Flash segment starts at end of BS, ends at 0x007FFE Secure space is 32K IW less BS: 100 = Standard security; secure program Flash segment starts at end of BS, ends at 0x00FFFE 000 = High security; secure program Flash segment starts at end of BS, ends at 0x00FFFE **(FOR 64K DEVICES)** X11 = No Secure program Flash segment Secure space is 4K IW less BS: 110 = Standard security; secure program Flash segment starts at end of BS, ends at 0x001FFE 010 = High security; secure program Flash segment starts at end of BS, ends at 0x001FFE Secure space is 8K IW less BS: 101 = Standard security; secure program Flash segment starts at end of BS, ends at 0x003FFE 001 = High security; secure program Flash segment starts at end of BS, ends at 0x003FFE Secure space is 16K IW less BS: 100 = Standard security; secure program Flash segment starts at end of BS, ends at 007FFEh 000 = High security; secure program Flash segment starts at end of BS, ends at 0x007FFE
RSS<1:0>	FSS	Immediate	Secure Segment RAM Code Protection bits 11 = No secure RAM defined 10 = Secure RAM is 256 bytes less BS RAM 01 = Secure RAM is 2048 bytes less BS RAM 00 = Secure RAM is 4096 bytes less BS RAM
GSS<1:0>	FGS	Immediate	General Segment Code-Protect bits 11 = User program memory is not code-protected 10 = Standard security; general program Flash segment starts at end of SS, ends at EOM 0x = High security; general program Flash segment starts at end of SS, ends at EOM

TABLE 26-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	**Supply Voltage**						
	VDD	—	3.0	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0-3.0V in 0.1s

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: This is the limit to which VDD can be lowered without losing RAM data.

TABLE 26-38: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑to SDOx Output High-Impedance(4)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{\text{SSx}}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.
3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCK clock generated by the Master must not violate this specificiation.
4: Assumes 50 pF load on all SPIx pins.

TABLE 26-40: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode(2)	0.2	—	μs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	—
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	μs	—
			400 kHz mode	—	1000	μs	—
			1 MHz mode(2)	—	400	μs	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode(2)	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	**See Note 3**

Note 1: BRG is the value of the I²C™ Baud Rate Generator. Refer to **Section 19. “Inter-Integrated Circuit (I²C™)”** (DS70195) in the “*dsPIC33F/PIC24H Family Reference Manual*”.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

TABLE 26-41: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min**	**Max**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	μs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode(1)	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.25	—	μs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.25	—	μs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	μs	—
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.6	—	μs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode(1)	250		ns	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode(1)	0.5	—	μs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

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